EXPRESS MAIL LABEL NO. 394059527 US

01-07-2005

102915278

12/21/04

Form PTO-1595
(Rev. 03/01)
OMB No. 0651-0027 (exp. 5/31/2002)

**RECORDATION FORM C**

## PATENTS ONL

COMMERCE
demark Office

Tab settings ⇨ ⇨ ⇨ ▼ ▼ ▼ ▼ ▼ ▼ ▼

To the Honorable Commissioner of Patents and Trademarks: Please record the attached original documents or copy thereof.

1. Name of conveying party(ies):

1) Tzu-Chiang Sung
2) Chih Po Huang
3) Rann Shyan Yeh
4) Jun Xiu Liu
5) Chi-Hsuen Chang
6) Chung-I Chen

Additional name(s) of conveying party(ies) attached? ☐ Yes ☑ No

2. Name and address of receiving party(ies)

Name: Taiwan Semiconductor Manufacturing Co., Ltd.

Internal Address: ________

Street Address: No. 8, Li-Hsin Road 6

Science Based Industrial Park

City: Hsin-Chu State: ____ Zip: ____

Country: Taiwan 300-77 R.O.C.

Additional name(s) & address(es) attached? ☐ Yes ☑ No

15535 U.S. PTO
11/019753
122104

3. Nature of conveyance:

☑ Assignment ☐ Merger

☐ Security Agreement ☐ Change of Name

☐ Other ________

Execution Date: 12/15/2004

4. Application number(s) or patent number(s):

If this document is being filed together with a new application, the execution date of the application is: 12/15/2004

A. Patent Application No.(s) ________

B. Patent No.(s) ________

Additional numbers attached? ☐ Yes ☑ No

5. Name and address of party to whom correspondence concerning document should be mailed:

Name: William H. Murray, Esquire

Internal Address: Duane Morris LLP

Street Address: One Liberty Place

City: Philadelphia State: PA Zip: 19103

6. Total number of applications and patents involved: 1

7. Total fee (37 CFR 3.41)..............$ 40.00

☐ Enclosed

☑ Authorized to be charged to deposit account

8. Deposit account number:

04-1679

**DO NOT USE THIS SPACE**

9. Signature.

Richard A. Paikoff
Name of Person Signing

Richard A. Paikoff
Signature

12/21/2004
Date

Total number of pages including cover sheet, attachments, and documents: 4

**Mail documents to be recorded with required cover sheet information to:**
Commissioner of Patents & Trademarks, Box Assignments
Washington, D.C. 20231

01/06/2005 GTON11 00000066 041679 11019753

01 FC:8021 40.00 DA

# ASSIGNMENT AND AGREEMENT

For value received, we, **Tzu-Chiang Sung, Chih Po Huang, Rann Shyan Yeh, Jun Xiu Liu, Chi-Hsuen Chang, Chung-I Chen** hereby sell, assign and transfer to **Taiwan Semiconductor Manufacturing Co., Ltd.**, with its principal place of business located at No. 8, Li-Hsin Road 6, Science-Based Industrial Park, Hsin-Chu, Taiwan 300-77, Republic of China, and its successors, assigns and legal representatives, the entire right, title and interest, for the United States of America, in and to certain inventions related to **N-WELL AND N$^+$ BURIED LAYER ISOLATION BY AUTO DOPING TO REDUCE CHIP SIZE** described in an application for Letters Patent of the United States and all the rights and privileges in said application and under any and all Letters Patent and any divisions, continuations, continuations-in-part, reexamination certificates, reissues, and extensions thereof that may be granted in the United States for said inventions; and we also concurrently hereby sell, assign and transfer to Taiwan Semiconductor Manufacturing Co., Ltd. the entire right, title and interest in and to said inventions for all countries foreign to the United States, including all rights of priority arising from the application aforesaid, and all the rights and privileges under any and all forms of protection, including Letters Patent, that may be granted in said countries foreign to the United States for said inventions.

We authorize Taiwan Semiconductor Manufacturing Co., Ltd. to make application for such protection in its own name and maintain such protection in any and all countries foreign to the United States, and to invoke and claim for any application for patent or other form of protection for said inventions, without further authorization from us, any and all benefits, including the right of priority provided by any and all treaties, conventions, or agreements.

We hereby consent that a copy of this assignment shall be deemed a full legal and formal equivalent of any document which may be required in any country in proof of the right of Taiwan Semiconductor Manufacturing Co., Ltd. to apply for patent or other form of protection for said inventions and to claim the aforesaid benefit of the right of priority.

We request that any and all patents for said inventions be issued to Taiwan Semiconductor Manufacturing Co., Ltd. in the United States and in all countries foreign to the United States, or to such nominees as Taiwan Semiconductor Manufacturing Co., Ltd. may designate.

We agree that, when requested, we shall, without charge to Taiwan Semiconductor Manufacturing Co., Ltd. but at its expense, sign all papers, and do all acts which may be necessary, desirable or convenient in connection with said applications, patents, or other forms of protection.

Inventor No. 1

Dated: 2004/12/15

Tzu-Chiang Sung

**Tzu-Chiang Sung**

Residence:

**No. 2, Alley 51, Lane 268, Sinmin St., Jhubei City 302, Taiwan, R.O.C.**

Inventor No. 2

Dated: 2004/12/15

Chih-Po Huang

**Chih Po Huang**

Residence:

**No. 38, Lane 9, Ankang St., HsinChu city 300, Taiwan, R.O.C.**

Inventor No. 3

Dated: 2004/12/15

Rann Shyan Yeh

**Rann Shyan Yeh**

Residence:

**No. 357-3, 6F, Nan-Ya St., Hsin-Chu City 300, Taiwan, R.O.C.**

Inventor No. 4

Dated: 2004/12/15 Jun Xiu Liu

**Jun Xiu Liu**

Residence:

**No. 25, Li-Hsin Rd., Hsinchu Science Park Hsinchu 300-77, Taiwan, R.O.C.**

Inventor No. 5

Dated: 2004/12/15 Chi-Hsuen Chang

**Chi-Hsuen Chang**

Residence:

**No. 20, Lane 278, Sec 2, Tiedao Rd., Hsinchu City 300, Taiwan, R.O.C.**

Inventor No. 6

Dated: 2004/12/15 Chung-I Chen

**Chung-I Chen**

Residence:

**8F, No. 32, Lane 2, Sec. 3, Jingguo Rd., Hsinchu City 300, Taiwan, R.O.C.**